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December 16, 2002

TO: Commissioner for Patents
Attn: Andy Huynh
Patent Examining Corps
Facsimile Center
Washington, D.C. 20231

FROM: Walter W. Nielsen

OUR REF: 884,319US1

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* Please deliver to Examiner Andy Huynh in Art Unit 2818. *

Document(s) Transmitted: Amendment and Response Under 37 CFR 1.111; Clean Version of Amended Specification Paragraphs; Clean Version of Pending Claims

Total pages of this transmission, including cover letter: 21

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In re Patent Application of: Biswajit Sur et al.

Examiner: Andy Huynh

Serial No.: 09/652,430

Group Art Unit: 2818

Filed: August 31, 2000

Docket No.: 884,319US1

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE

Please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

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Reg. No.: Reg. No. 25,539

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Walter W. Nielsen

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Dec. 16, 2002

Date of Transmission

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Biswajit Sur et al.

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicants have reviewed the Office Action mailed on September 16, 2002. Please amend the above-identified patent application as follows.

IN THE SPECIFICATION

Please make the paragraph substitutions indicated in the appendix entitled "Clean Version of Amended Specification Paragraphs". The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs.

The sub-title on page 1, line 8 is amended as follows: Technical Field [of the Invention]

The paragraph beginning on page 1, line 10 is amended as follows:

Embodiments of the [The] present invention relate [relates] generally to electronics packaging. More particularly, the present invention relates to an electronic assembly that includes an integrated circuit package comprising a solderable thermal interface between the integrated circuit and a heat spreader to dissipate heat generated in a high speed integrated circuit, and to manufacturing methods related thereto.

The sub-title on page 1, line 16 is amended as follows: Background Information [of the Invention]